Special Issue

Tactile Sensing Technology and Systems, Volume II

Message from the Guest Editor

Tactile sensors acquire tactile information through physical touch; measurands are, for example, temperature, vibration, softness, texture, shape, composition, and shear and normal forces. Electronic/artificial skin comprises embedded electronic systems which integrate tactile sensing arrays, signal acquisition, data processing and decoding, and which can transmit collated information. Such electronic/artificial skin will become one of the main sensing essentials in prosthetics, bionics, robotics, virtual reality, haptic devices, IoT, etc. In this Special Issue, we focus on both insights and advancements in tactile sensing with the goal of bridging different research areas, e.g., material science, electronics, robotics, neuroscience, mechanics, sensors, MEMS/NEMS, addictive and 3D manufacturing, and bio- and neuro-engineering. We would like to receive commentaries, perspectives, and insightful reviews on related topics as well as technological breakthroughs of original works and civil and industrial applications in both short communications and full papers.

Guest Editor

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